50/83873/164malf

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

KAWAGOE, et al.

Filed:

December 14, 2001

For:

PROCESS FOR MANUFACTURING A

SEMICONDUCTOR WAFER, A SEMICONDUCTOR

WAFER, PROCESS FOR MANUFACTURING A

SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE,

AND SEMICONDUCTOR INTEGRATED CIRCUIT

DEVICE

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents Washington, D.C. 20231

December 14, 2001

Sir:

Please amend the above-identified application, prior to examination thereof, as follows:

IN THE SPECIFICATION

Page 1, after the title and prior to the heading "BACKGROUND OF THE INVENTION", please insert the following:



--This application is a Divisional application of application Serial No. 09/513,349, filed February 25, 2000, which is a Continuation application of application Serial No. 08/934,774, filed September 22, 1997, now U.S. Patent



No. 6,043,114, which is a Divisional application of application Serial No.

08/508,483, filed July 28, 1995.--